

GL100MN_xMP Series

Compact, Surface Mount Type Infrared Emitting Diode

■ Features

1. Compact and thin package
2. Surface mount type
3. 2-way mounting; top view/side view
4. Reflow soldering
5. High output type: **GL100MN1MP**
6. General purpose type: **GL100MN0MP**
Pair use with **PT100MC0MP/PT100MF0MP** is recommended

■ Applications

1. Touch panel for ATM
2. Touch panel for Car navigation system
3. Touch panel for FA equipment

■ Absolute Maximum Ratings (T_a=25°C)

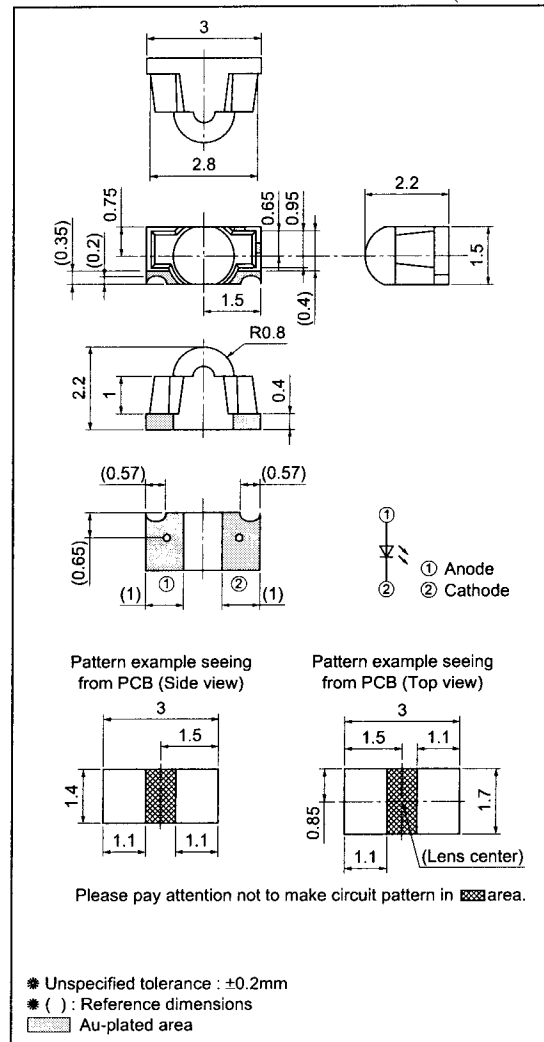
Parameter	Symbol	Rating	Unit
Forward current	I _F	50	mA
*1 Peak forward current	I _{FM}	0.5	A
Reverse voltage	V _R	6	V
Power dissipation	P	75	mW
Operating temperature	T _{opr}	-30 to +85	°C
Storage temperature	T _{slg}	-40 to +95	°C
*2 Soldering temperature	T _{sol}	240	°C

*1 Pulse width 100μs, duty 0.01

*2 Max. 10s

■ Outline Dimensions

(Unit : mm)



■ Electro-optical Characteristics

(T_a=25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Forward voltage	GL100MN0MP V _F	I _F =20mA	—	1.2	1.4	V
	GL100MN1MP V _F	I _F =20mA	—	1.2	1.5	V
Peak forward voltage	V _{FM}	I _{FM} =0.5A	—	3.0	4.0	V
Reverse current	I _R	V _R =3V	—	—	10	μA
Radiant flux	GL100MN0MP Φ _e	I _F =20mA	1.0	—	3.0	mW
	GL100MN1MP Φ _e	I _F =20mA	2.0	—	6.0	mW
Peak emission wavelength	λ _p	I _F =5mA	—	940	—	nm
Half intensity wave length	Δλ	I _F =5mA	—	45	—	nm
Terminal capacitance	C _t	V _R =0, f=1MHz	—	50	—	pF
Response frequency	f _c	—	—	300	—	kHz
Half intensity angle	Δθ	—	—	±10	—	°

Fig.1 Forward Current vs. Ambient Temperature

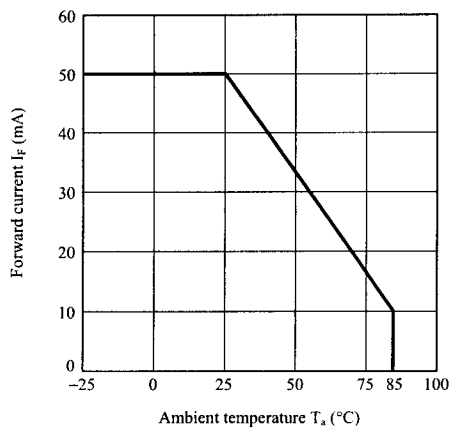


Fig.2 Peak Forward Current vs. Duty Ratio

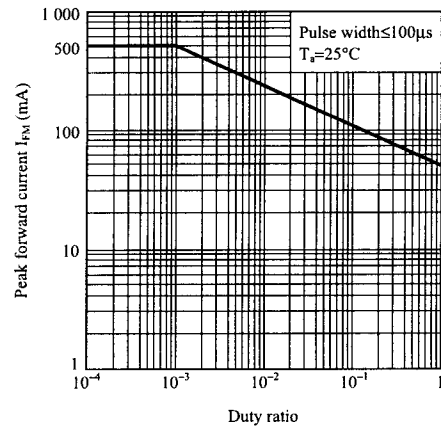


Fig.3 Spectral Distribution

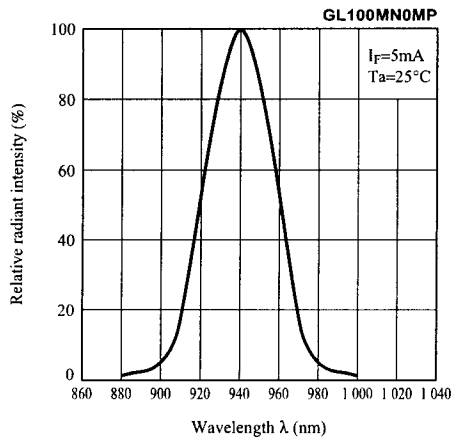


Fig.4 Spectral Distribution

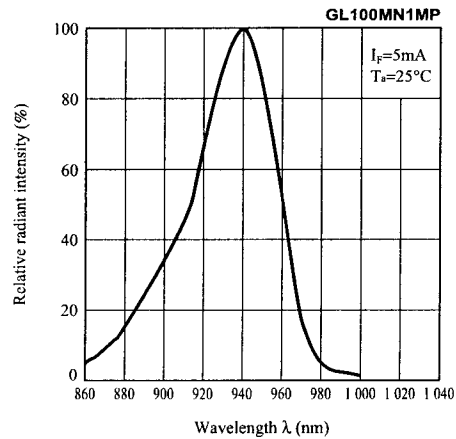


Fig.5 Peak Emission Wavelength vs. Ambient Temperature

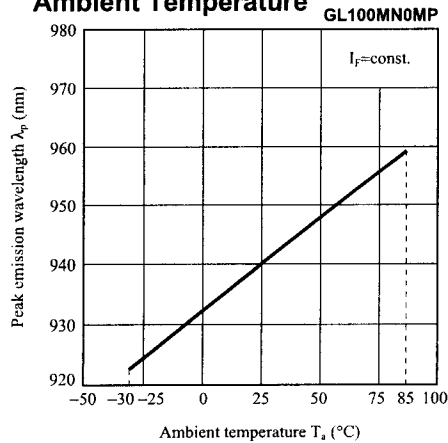


Fig.6 Peak Emission Wavelength vs. Ambient Temperature

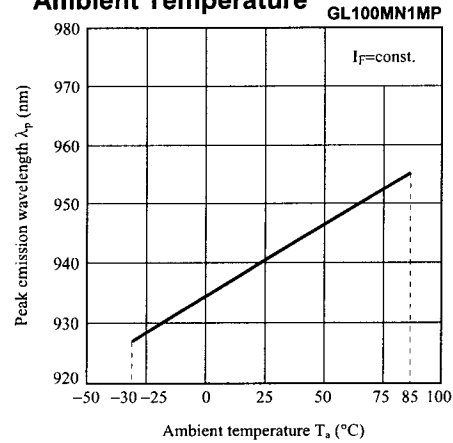


Fig.7 Forward Current vs. Forward Voltage

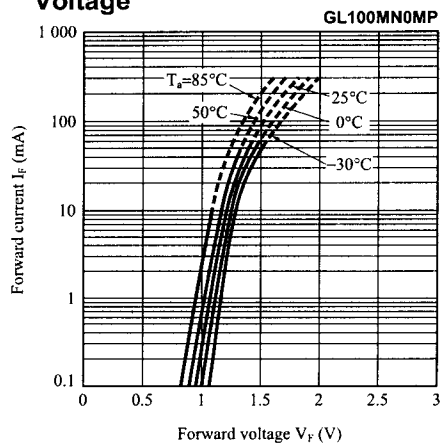


Fig.8 Forward Current vs. Forward Voltage

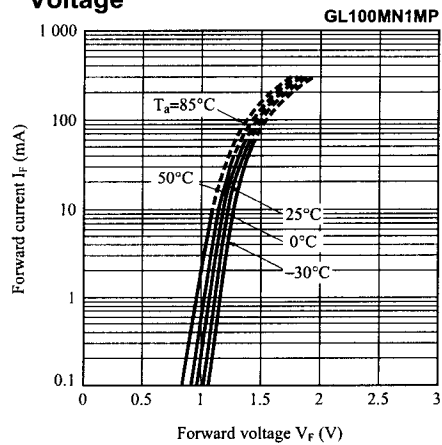


Fig.9 Relative Radiant Flux vs. Ambient Temperature

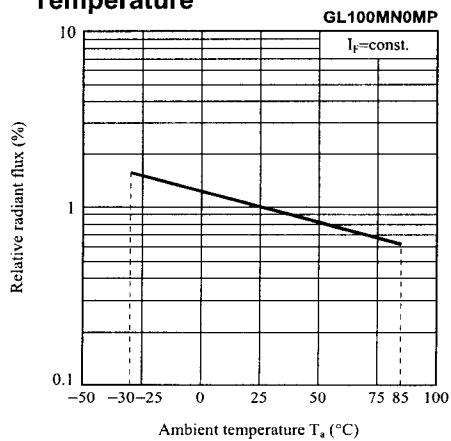


Fig.10 Relative Radiant Flux vs. Ambient Temperature

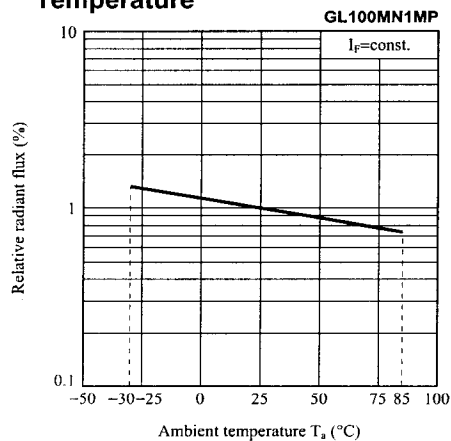


Fig.11 Radiant Flux vs. Forward Current

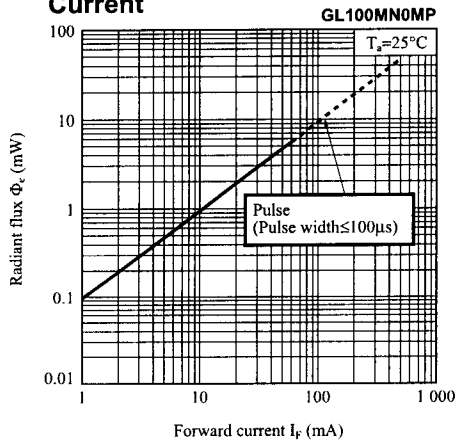


Fig.12 Radiant Flux vs. Forward Current

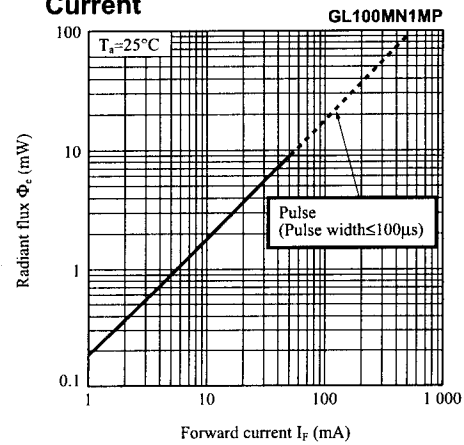


Fig.13 Relative Output vs. Distance To Detector

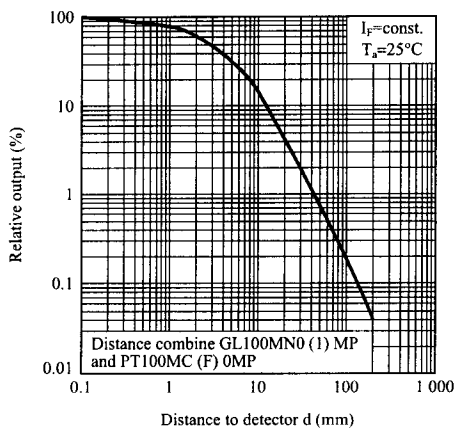


Fig.14 Radiation Diagram (Typical Value)

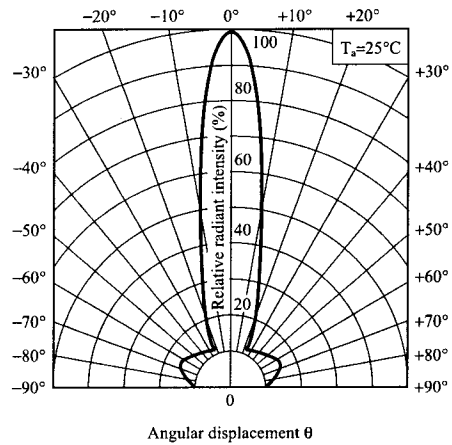
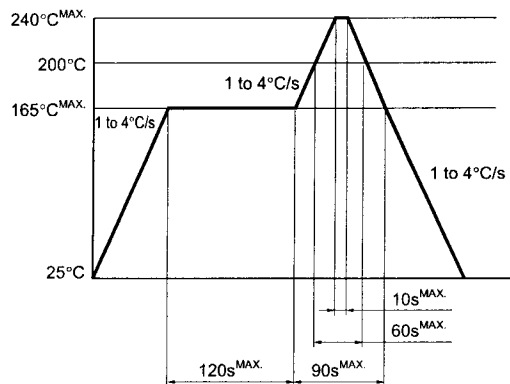


Fig.15 Reflow Soldering

Only one time soldering is recommended within the temperature profile shown below.

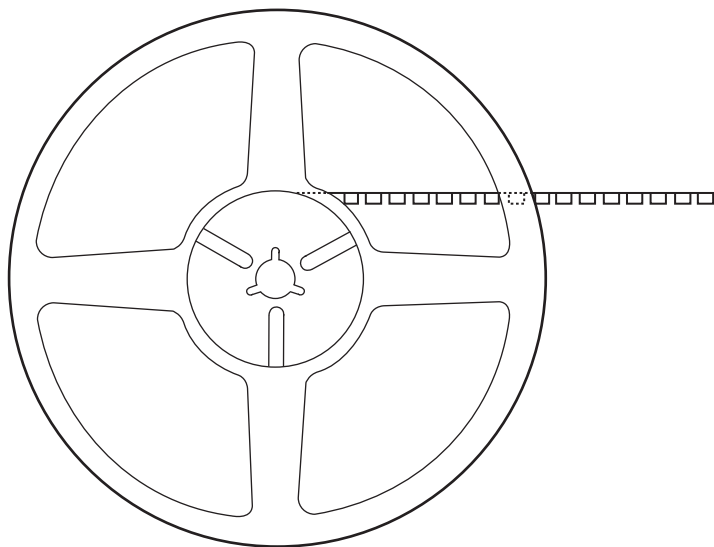


NOTICE

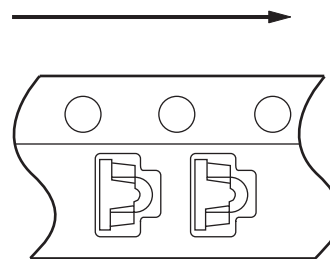
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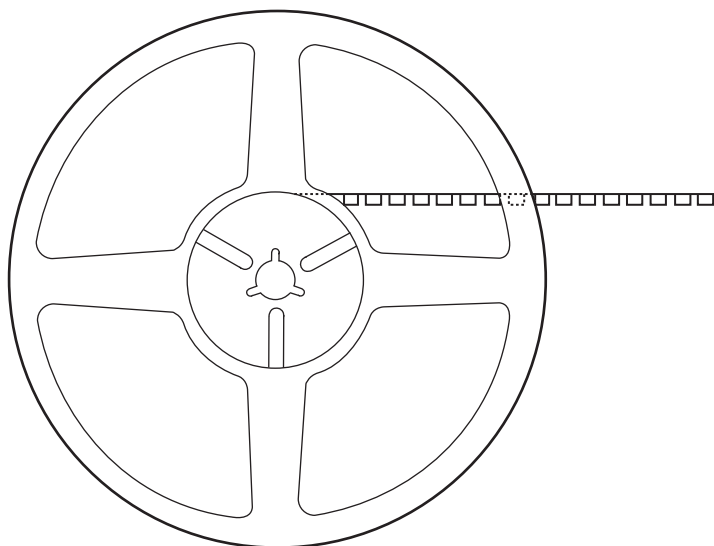
GL100xxxxP }
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PULL-OUT DIRECTION



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PD100xxxxP1 } 1,500 Pieces per reel
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